



## **CyberOptics Unveils WX3000™ Metrology and Inspection System for Semiconductor Wafer-Level and Advanced Packaging at Virtual SEMICON West**

*WX3000 Systems Incorporate Proprietary NanoResolution MRS™ Sensor Technology*

**Minneapolis, Minnesota** — July 8, 2020 — [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions, will unveil the new Multi-Reflection Suppression™ (MRS™)-enabled 3D and 2D WX3000 Metrology and Inspection systems for wafer-level and advanced packaging applications at the virtual SEMICON West show, July 20-23<sup>rd</sup>.

Incorporating the [NanoResolution MRS sensor](#), the WX3000 Metrology and Inspection systems enable the ultimate combination of high speed, high resolution and high accuracy for wafer-level and advanced packaging, to improve yields and productivity.

Performing two to three times faster than alternate technologies at data processing speeds in excess of 75 million 3D data points per second, the NanoResolution MRS sensor-enabled WX3000 systems deliver throughput greater than 25 wafers per hour. 100% 3D and 2D metrology and inspection can be completed simultaneously at high speed, as compared to an alternate, slow method that requires two separate scans for 3D and 2D and only a sampling of a few die.

The proprietary NanoResolution MRS sensor, deemed best in class, meticulously identifies and rejects multiple reflections caused by shiny and mirror-like surfaces. Effective suppression of multiple reflections is critical for highly accurate measurements.

“With the growing complexity and variety of advanced packaging, the need for highly accurate, 100% 3D and 2D metrology and inspection continues to increase,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics, “Our MRS-Enabled WX3000 systems provide not only high resolution and high accuracy, they perform 2-3x faster than alternative technologies.”

WX3000 systems are designed specifically for various wafer-level and advanced packaging applications including wafer bumps, solder balls and bumps, gold bumps and copper pillars. The systems provide superior measurement and inspection performance for features down to 25-micron, including bump height, coplanarity, diameter and shape, relative location and a variety of other measurements.

CyberOptics will launch a WX3000 system for 12” and 8” wafers and a WX3000 system for 8” and 6” wafers.

For more information, visit [www.cyberoptics.com](http://www.cyberoptics.com).

### **About CyberOptics**

CyberOptics Corporation ([www.cyberoptics.com](http://www.cyberoptics.com)) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics’ sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By

leveraging its leading edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible world-wide recession or depression resulting from the economic consequences of the Covid-19 pandemic; the negative effect on our revenue and operating results of the Covid-19 crises on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and other countries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled SQ3000 Multi-Function systems and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 Multi-Function inspection and measurement systems and products for semiconductor advanced packaging inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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